

February 1992 Revised June 2001

74LVQ273

Low Voltage Octal D-Type Flip-Flop

General Description

The LVQ273 has eight edge-triggered D-type flip-flops with individual D inputs and Q outputs. The common buffered Clock (CP) and Master Reset $(\overline{\text{MR}})$ input load and reset (clear) all flip-flops simultaneously.

The register is fully edge-triggered. The state of each D input, one setup time before the LOW-to-HIGH clock transition, is transferred to the corresponding flip-flop's Q output.

All outputs will be forced LOW independently of Clock or Data inputs by a LOW voltage level on the MR input. The device is useful for applications where the true output only is required and the Clock and Master Reset are common to all storage elements.

Features

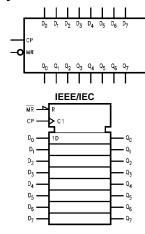
- Ideal for low power/low noise 3.3V applications
- Implements patented EMI reduction circuitry
- Available in SOIC JEDEC, SOIC EIAJ and QSOP packages
- Guaranteed simultaneous switching noise level and dynamic threshold performance
- Improved latch-up immunity
- \blacksquare Guaranteed incident wave switching into 75 Ω
- 4 kV minimum ESD immunity

Ordering Code:

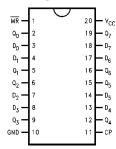
Order Number	Package Number	Package Description
74LVQ273SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74LVQ273SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74LVQ273QSC	MQA20	20-Lead Quarter Size Outline Package (QSOP), JEDEC MO-137, 0.150" Wide

Devices also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code

Logic Symbols



Connection Diagram



Pin Descriptions

Pin Names	Description				
D ₀ –D ₇	Data Inputs				
MR	Master Reset				
CP	Clock Pulse Input				
Q ₀ –Q ₇	Data Outputs				

Absolute Maximum Ratings(Note 1)

Supply Voltage (V $_{CC}$) -0.5V to +7.0V

DC Input Diode Current (I_{IK})

 $\begin{array}{ccc} V_{I} = -0.5 V & -20 \text{ mA} \\ V_{I} = V_{CC} + 0.5 V & +20 \text{ mA} \\ \text{DC Input Voltage (V_{I})} & -0.5 V \text{ to } V_{CC} + 0.5 V \end{array}$

DC Output Diode Current (I_{OK})

DC Output Voltage (V_O) -0.5V to $V_{CC} + 0.5V$

DC Output Source

or Sink Current (I_O) ± 50 mA

DC V_{CC} or Ground Current

 $(I_{CC} \text{ or } I_{GND})$ $\pm 400 \text{ mA}$

Storage Temperature (T_{STG}) $-65^{\circ}C$ to $+150^{\circ}C$

DC Latch-up Source or

Sink Current ±300 mA

Recommended Operating Conditions (Note 2)

 $\begin{array}{lll} \text{Supply Voltage (V}_{\text{CC}}) & 2.0 \text{V to } 3.6 \text{V} \\ \text{Input Voltage (V}_{\text{I}}) & 0 \text{V to V}_{\text{CC}} \\ \text{Output Voltage (V}_{\text{O}}) & 0 \text{V to V}_{\text{CC}} \end{array}$

Operating Temperature (T_A) $-40^{\circ}C$ to $+85^{\circ}C$

Minimum Input Edge Rate $\Delta V/\Delta t$

 $V_{\mbox{\scriptsize IN}}$ from 0.8V to 2.0V

 $V_{CC} @ 3.0V$ 125 mV/ns

Note 1: The "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the absolute maximum ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Note 2: Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

Symbol	Parameter	V _{CC} T _A = +25°C		$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	Units	Conditions	
Symbol		(V)	Тур	Gua	Guaranteed Limits		Conditions
V _{IH}	Minimum High Level Input Voltage	3.0	1.5	2.0	2.0	V	V _{OUT} = 0.1V or V _{CC} - 0.1V
V _{IL}	Maximum Low Level Input Voltage	3.0	1.5	0.8	0.8	V	V _{OUT} = 0.1V or V _{CC} - 0.1V
V _{OH}	Minimum High Level	3.0	2.99	2.9	2.9	V	$I_{OUT} = -50 \mu A$
	Output Voltage	3.0		2.58	2.48	V	$V_{IN} = V_{IL} \text{ or } V_{IH} \text{ (Note 3)}$ $I_{OH} = -12 \text{ mA}$
V _{OL}	Maximum Low Level	3.0	0.002	0.1	0.1	V	I _{OUT} = 50 μA
	Output Voltage	3.0		0.36	0.44	V	$V_{IN} = V_{IL} \text{ or } V_{IH} \text{ (Note 3)}$ $I_{OL} = 12 \text{ mA}$
I _{IN}	Maximum Input Leakage Current	3.6		±0.1	±1.0	μА	$V_I = V_{CC},$ GND
I _{OLD}	Minimum Dynamic	3.6			36	mA	V _{OLD} = 0.8V Max (Note 5)
I _{OHD}	Output Current (Note 4)	3.6			-25	mA	V _{OHD} = 2.0V Min (Note 5)
I _{CC}	Maximum Quiescent Supply Current	3.6		4.0	40.0	μΑ	$V_{IN} = V_{CC}$ or GND
V _{OLP}	Quiet Output Maximum Dynamic V _{OL}	3.3	0.4	0.8		٧	(Note 6)(Note 7)
V _{OLV}	Quiet Output Minimum Dynamic V _{OL}	3.3	-0.3	-0.8		٧	(Note 6)(Note 7)
V _{IHD}	Maximum High Level Dynamic Input Voltage	3.3	1.7	2.0		٧	(Note 6)(Note 8)
V _{ILD}	Maximum Low Level Dynamic Input Voltage	3.3	1.6	0.8		٧	(Note 6)(Note 8)

Note 3: All outputs loaded; thresholds on input associated with output under test.

Note 4: Maximum test duration 2.0 ms, one output loaded at a time.

Note 5: Incident wave switching on transmission lines with impedances as low as 75Ω for commercial temperature range is guaranteed for.

Note 6: Worst case package.

Note 7: Max number of outputs defined as (n). Data Inputs are driven 0V to 3.3V; one output at GND.

Note 8: Max number of Data Inputs (n) switching. (n - 1) inputs switching 0V to 3.3V. Input-under-test switching: 3.3V to threshold (V_{ILD}), 0V to threshold (V_{IHD}), f = 1 MHz.

AC Electrical Characteristics

	Parameter		$T_A = +25$ °C $C_L = 50 \text{ pF}$			$T_A = -40$ °C to +85°C $C_L = 50$ pF		Units	
Symbol		V _{CC}							
		(V)	Min	Тур	Max	Min	Max		
f _{MAX}	Maximum Clock	2.7	50			45		MHz	
	Frequency	3.3 ± 0.3	90			75			
t _{PLH}	Propagation Delay	2.7	4.0	9.6	17.6	3.0	20.0	ns	
	CP to Q _n	3.3 ± 0.3	4.0	8.0	12.5	3.0	14.0	115	
t _{PHL}	Propagation Delay	2.7	4.0	10.2	18.3	3.5	20.5		
	CP to Q _n	3.3 ± 0.3	4.0	8.5	13.0	3.5	14.5	ns	
t _{PHL}	Propagation Delay	2.7	4.0	10.2	18.3	3.5	20.0		
	MR to Q _n	3.3 ± 0.3	4.0	8.5	13.0	3.5	14.0	ns	
toshl	Output to Output	2.7		1.0	1.5		1.5	ns	
toslh	Skew (Note 9)	3.3 ± 0.3		1.0	1.5		1.5	115	

Note 9: Skew is defined as the absolute value of the difference between the actual propagation delay for any two outputs within the same packaged device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}). Parameter guaranteed by design. Not tested.

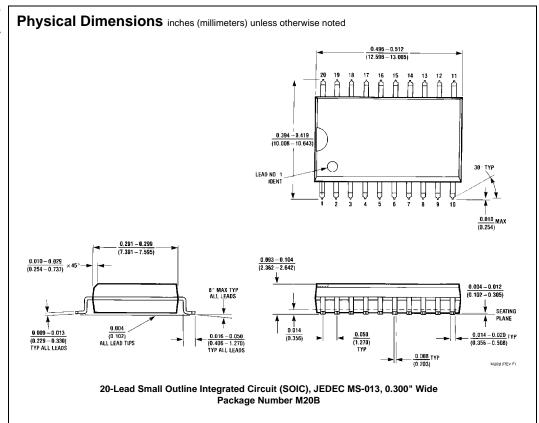
AC Operating Requirements

Symbol	Parameter	v _{cc}	T _A = +25°C C _L = 50 pF		$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $C_L = 50 \text{ pF}$	Units	
		(V)	Тур	Guaranteed Minimum			
t _S	Setup Time, HIGH or LOW	2.7		6.5	8.5		
	D _n to CP	3.3 ± 0.3		5.0	6.0	ns	
t _H	Hold Time, HIGH or LOW	2.7		0.0	0.0		
	D _n to CP	3.3 ± 0.3		0.0	0.0	ns	
t _W	Clock Pulse Width	2.7		7.0	8.5		
	HIGH or LOW	3.3 ± 0.3		5.5	6.0	ns	
t _W	MR Pulse Width	2.7		7.0	8.5		
	HIGH or LOW	3.3 ± 0.3		5.5	6.0	ns	
t _W	Recovery Time	2.7		5.0	6.5		
	MR to CP	3.3 ± 0.3		4.0	4.5	ns	

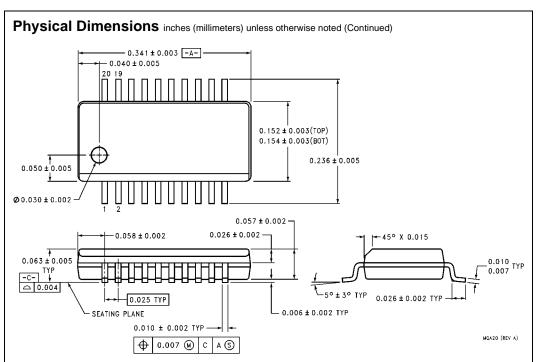
Capacitance

Symbol	Parameter	Тур	Units	Conditions
C _{IN}	Input Capacitance	4.5	pF	V _{CC} = Open
Cpp (Note 10)	Power Dissipation Capacitance	35	pF	$V_{CC} = 3.3V$

Note 10: C_{PD} is measured at 10 MHz.



Physical Dimensions inches (millimeters) unless otherwise noted (Continued) 12.6±0.10 0.40 TYP --A-5.3±0.10 9.27 TYP 7.8 -B-3.9 0.2 C B A ALL LEAD TIPS 10 PIN #1 IDENT.-0.6 TYP 1.27 TYP LAND PATTERN RECOMMENDATION ALL LEAD TIPS SEE DETAIL A 0.1 C 1.8±0.1 -C-L _{0.15±0.05} 0.15-0.25 -1.27 TYP 0.35-0.51 ⊕ 0.12 **(** C A DIMENSIONS ARE IN MILLIMETERS GAGE PLANE 0.25 NOTES: A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998. B. DIMENSIONS ARE IN MILLIMETERS. C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS. 0.60±0.15 SEATING PLANE 1.25 -M20DRevB1 DETAIL A 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide Package Number M20D



20-Lead Quarter Size Outline Package (QSOP), JEDEC MO-137, 0.150" Wide Package Number MQA20

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